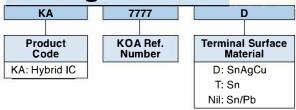


## features

- Adjustment processes are decreased by function and ratio trimmings
- Various types of package are available
- High reliability achieved by KOAs original thick film technology

## ordering information



## Component - KA Series

|                            | Item                                   | Printing                        | Mounting                | Bonding        |
|----------------------------|--|---------------------------------|-------------------------|----------------|
| Substrate Materials        | Al <sub>2</sub> O <sub>3</sub> Alumina | 0                               | 0                       | 0              |
|                            | Glass epoxy                            | x                               | 0                       | 0              |
| Conductors, Resistors      | Item                                   | Ag-Pd                           | Ag-Pt                   |                |
|                            | Conductor resistance                   | 18mΩ/□/15μm                     | 5mΩ/□/10μm              |                |
|                            | Heat shock                             | -55°C~+125°C 300 Cycles         | -55°C~+125°C 500 Cycles |                |
|                            | Printed Resistor                       | 5Ω~10MΩ ±100x10 <sup>6</sup> /K |                         |                |
| Mounting                   | Item                                   | Specifications                  |                         |                |
|                            | BGA                                    | 0.5mm Pitch~                    |                         |                |
|                            | QFP                                    | 0.4mm Pitch~                    |                         |                |
|                            | Chip                                   | 0.4mm x 0.2mm                   |                         |                |
| Package, Outside Terminals | Package                                | Lead Pitch                      |                         |                |
|                            | SIP                                    | 1.8mm, 2.0mm, 2.5mm, 2.54mm     |                         |                |
|                            | DIP, SOP                               | 1.27mm, 1.8mm, 2.54mm           |                         |                |
|                            | ZIP                                    | 2.54mm                          |                         |                |
|                            | BGA, LGA                               | 1.0mm~                          | ·                       |                |
| Over Coating, Plating      | Over Coating                           | Color                           |                         | UL Standard    |
|                            | Epoxy metamorphic phenol               | Black 94 V0 Approved            |                         | 94 V0 Approved |
|                            | Epoxy                                  | Black                           |                         | 94 V1 Approved |

o= Available x= Not available